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FOR IMMEDIATE RELEASE

Press Release

SEMICON WEST 2015 is 2 WEEKS AWAY! VISIT YINCAE BOOTH 6072 AT SEMICON WEST

(Albany, NY) June 30, 2015 – The SEMICON West 2015, North America's premier Microelectronics event is less than two weeks away! SEMICON West 2015 will be held at the Moscone Center in San Francisco, CA from July 14th to 16th. We sincerely invite you to stop by our Booth 6072 to learn more about YINCAE Advanced Materials.

YINCAE offers a variety of exclusive Adhesives, Thermal Interface, and Chip/Board/Packaging level materials that have been adopted by leading contract manufacturers and Tier 1 Microelectronic suppliers. YINCAE innovated the **WORLD's FIRST** Lead-Free Solder Joint Encapsulation Adhesive solutions for wafer level, flip chip, POP, LGA, BGA and many more applications. YINCAE offers SJEA for low, medium, and high temperature solder alloy applications for your individualized needs.

YINCAE Advanced Materials, LLC hopes that you are finalizing preparation for the SEMICON WEST 2015. We are looking forward to seeing you in the **North Hall at booth 6072** and will be available to talk about our products and answer any questions that you may have. We hope that you will join us at the conference to learn about YINCAE and the products that we have to offer. We have exclusive products that no other company has developed. We look forward to seeing you at booth 6072!

If you wish to visit the official website of YINCAE Advanced Materials, LLC, please visit us by clicking the following link: <u>YINCAE Website</u>.

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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